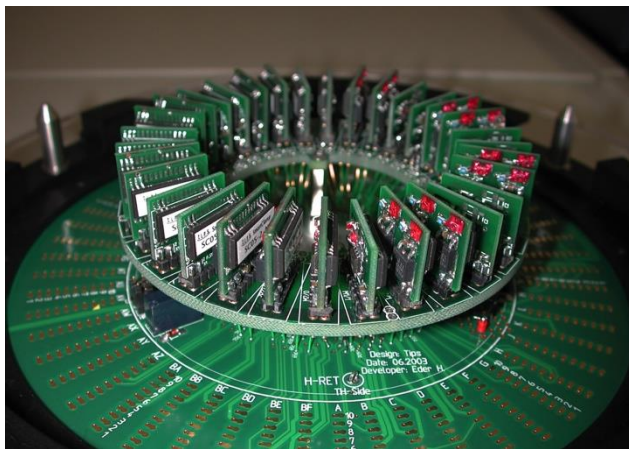


Vertical Probe Cards for High Current Devices, Automotive ASICS, Mixed Signal, RF (RADAR) and Sensor ICs

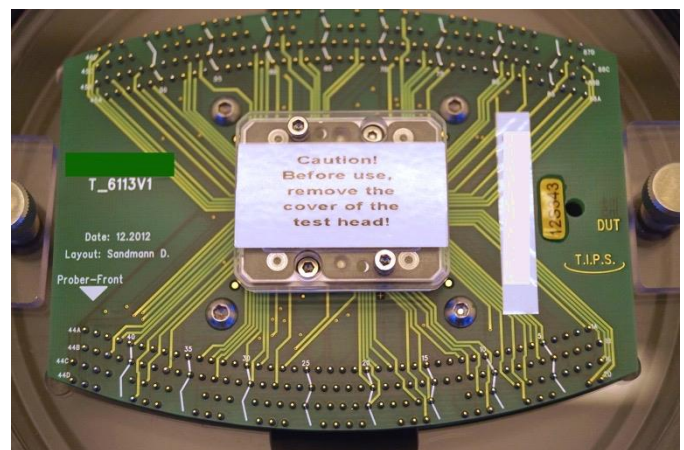


High Current Vertical Probe Card with "SmartClamp" protected power outputs, dual die configuration

Applications characterised by combinations of logic circuitry and power outputs sharing the same die give special challenges for probe cards design and manufacturing – high density, fine pitch bond pads for the logic part in combination with hefty currents to be tested going up to several Amperes.

T.I.P.S.' vertical probe cards are specifically developed to address these requirements:

- Low resistance and high current carrying capability probes.
- SmartClamp probes protection technology allows safe testing of high test currents and protects probes and D.U.T. from overcurrent spikes.



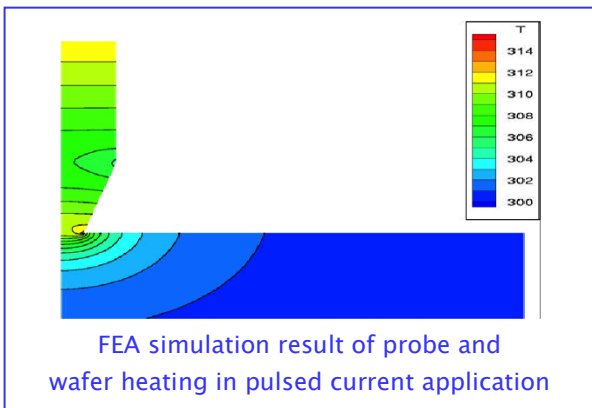
High Pincount Probe Head for "Automotive" ASIC



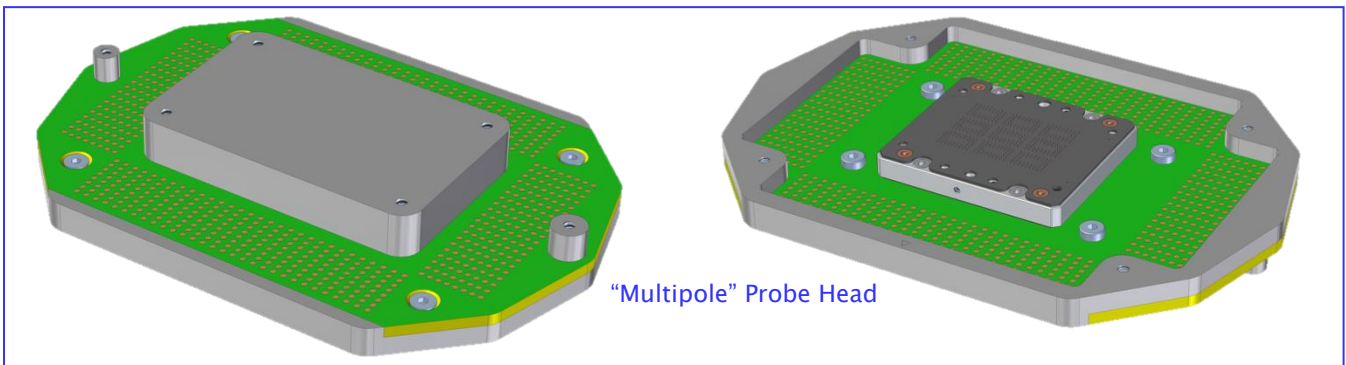
- High Frequency Interposer design and probes arrangement allow for RF-bandwidth of more than 5 GHz with robust buckling beam vertical probes technology



Vertical Probe Head for Automotive RADAR
 - dual site
 - 3 GHz signal bandwidth
 - 77 GHz RADAR through probes

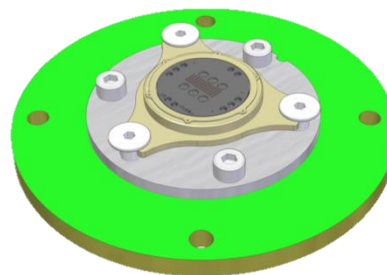


- Advanced interposer technology allows for high trace currents and good signal integrity.
 - Numerical simulation of probe and wafer contact heating enables to define S.O.A.R. (safe operating area) in pulsed and DC high current application.



"Multipole" Probe Head

- State-of-the-art CAD and EDA design tools allow for a smooth integration into your test environment.



"Vertical LuPo" for MEMS Pressure Sensors